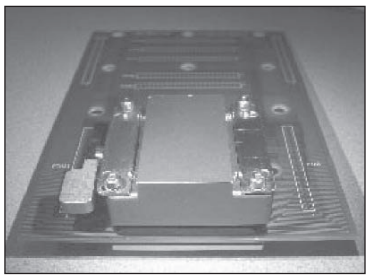
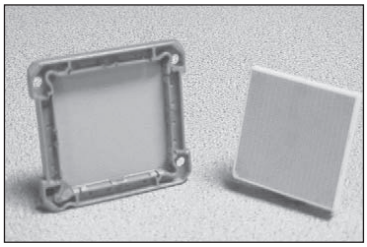


New technology is driving the need for high performance test sockets.



ET's 40 GHz High Performance Socket is designed for the high speed testing environment.

Ordering Information Example

CON=Contactor or Pin Count — Package Code — Internal Use — Grid Size

HSP-900-3BG031-PF

HSP: High Speed Socket; 900: Lead Pitch; 3BG031: Grid Size; PF: Internal Use

Material Electrical Specifications	
Bandwidth	40 GHz min.
Inductance	0.0232 pF
Contact Resistance	< 25m ohms @ < 40 grams/contact
Insulation Resitance 500V DC	1000m ohm @ 1.27mm pitch
Signal to Ground Resistance	Z_o = 55 ohms
Insulation Resistence 500V DC	1000m ohm @ 1.00mm pitch
Votage Breakdown (DWV)	1000V min. @ 1.00mm pitch
Current Rating	2.5A/pin @ 1.00mm pitch
Material Reliability Specifications	
Individual Contact Force	40-50 grams/contact
Durability	500,000 minimum
Materials	
Contact	Anisotropically conductive polymer fabric with multiple conductive elements
Operating Temperature	
Temperature Range	-55 degrees C to +150 degrees C

Information Required for Ordering:

- Package outline drawing needed, including pin counts, ball pitch & grid layout

Sample Part #: S-BGA-16-292-A

NOTE: Manufacturer's chip package drawing required with each order.

CUSTOM 40 GHz ZIF SOCKETS

ET's high performance sockets allow the user to test, debug or program any BGA or MicroBGA accommodating lead pitches as small as 0.40mm and as large as 5.00mm. These sockets are designed for outstanding electrical performance at high speeds.

FEATURES & BENEFITS

- Anisotropically conductive polymer fabric with multiple conductive elements per interface for outstanding electrical performance
- Electrical performance tested to 40 GHz
- Self-registering, compliant material eliminates a whole level of tolerance stack-up and makes implementation easy
- Reduces costs/labor; no need for precision alignment of contacts
- Robust, durable interface material that is extremely stable
- Ideal for high-density, high reliability interconnections with capabilities to 0.1mm interfaces
- Excellent alternative for testing fine-pitch chip packages and bare boards with surface-mount pads
- Allows for non-planar interconnections; easily cut or molded to accommodate varying dimensional sizes and geometric configurations

APPLICATIONS

- High Speed Test and Development
- High Speed Test & Burn-in
- Production Sockets
- Board to Board Connectors
- Cable to Board Connectors

BALL PITCH

- BGA (1.27mm through 5.0mm)
- mBGA (1.50mm, 1.00mm, 0.80mm, 0.75mm, 0.65mm, 0.50mm, 0.40mm)

Looking for a custom PCB? Request an immediate custom quotation online for a prompt response:
Web Link: www.1800adapter.com/forms

For a complete list of High Performance Socket specifications, pricing and delivery information, please see:
Web Link: www.1800adapter.com/133